



Case: AMKOR-045A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suk Sing Jang

) Group No.: 2826

Serial No.: 09/687,493

)

Filed: 10/13/2000

)

For: Semiconductor Package Having Improved  
Adhesiveness and Ground Bonding

)

Examiner:  
Williams, Alexander

#17/B  
~~(In to Drafts And)~~  
JMC/Am  
6/25/03

RESPONSE TO OFFICE ACTION

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

In response to the Office Action mailed March 6, 2003, in relation to the above-identified patent application, please amend the application as follows:

RECEIVED  
JUN 12 2003

TECHNOLOGY CENTER 2800